



Material Content Data Sheet



Sales Product Name		BTS5020-2EKA		Issued		29. August 2013		
MA#		MA001130428						
Package		PG-DSO-14-40		Weight*		150.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.067	2.71	2.71	27075	27075
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		463	
	non noble metal	iron	7439-89-6	1.392	0.93		9266	
wire	non noble metal	copper	7440-50-8	56.512	37.62	38.61	376222	386067
	non noble metal	copper	7440-50-8	1.239	0.82	0.82	8247	8247
	encapsulation	organic material	carbon black	1333-86-4	0.166	0.11		1107
	plastics	epoxy resin	-	7.646	5.09		50905	
	inorganic material	silicondioxide	60676-86-0	75.300	50.14	55.34	501305	553317
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8163	8163
plating	noble metal	silver	7440-22-4	1.417	0.94	0.94	9437	9437
glue	plastics	epoxy resin	-	0.202	0.13		1346	
	noble metal	silver	7440-22-4	0.953	0.63	0.76	6348	7694
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com